



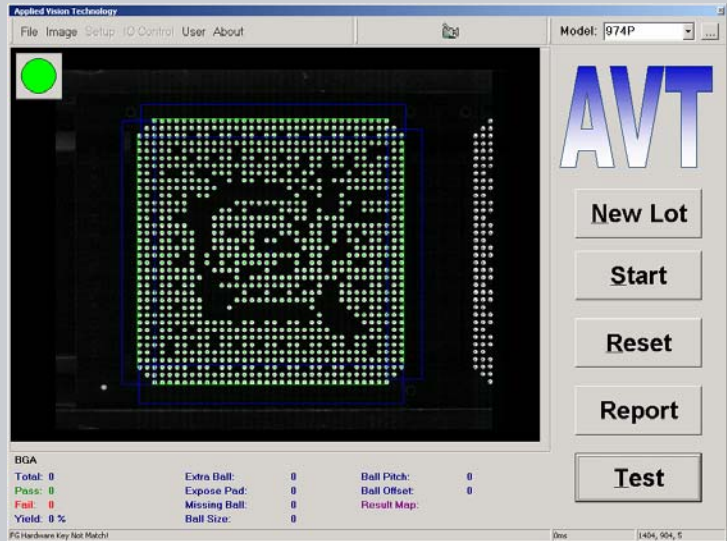
PI-1000B 2D BGA Inspection System

Overview

PI-1000B 2D is an inspection system for measurement of 2D Ball Grid Arrays

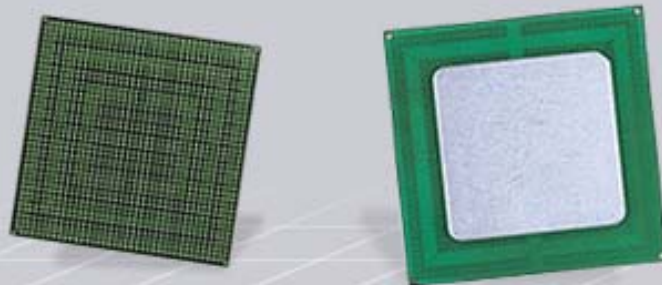
Feature

1. Simple setup
2. Easy calibration procedure.
3. Defects images log. Up to 10 defects images will be saved.
4. Inspects up to two thousand solder balls per second.
5. Handles a variety of BGA, CSP, and flip chip device types

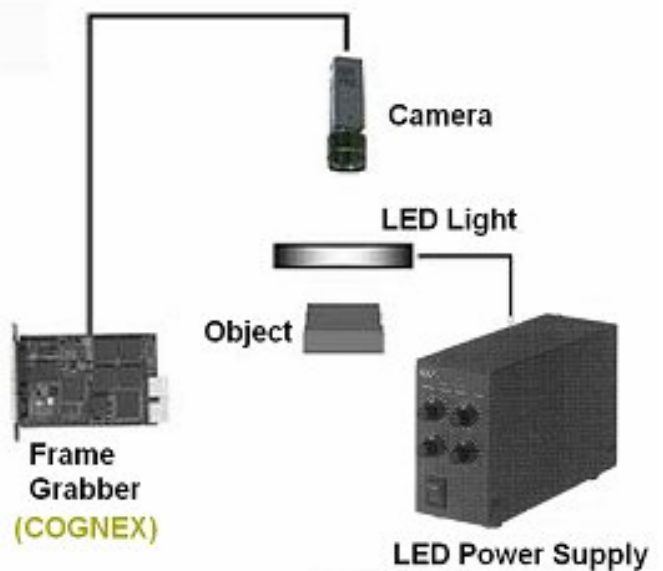


Inspection Capabilities

| Measured items | Max. comp. Size (50 x 50 mm) |
|----------------|---|
| | Description |
| Missing Ball | Check for ball absence, discriminates between round ball and round pad |
| Extra Ball | Check for additional ball, discriminates between round ball and round pad |
| Ball Size | Differential the Ball size from 0.50 mm, 0.64 mm and 0.75 mm. |
| Ball Position | Reference from a corner ball |
| Ball Pitch | Ball center to next ball center in both X & Y axis |



The Systems and Components



Inspection System Hardware

- High-Speed Vision Controller
- Cameras (Standard or High Resolution)
- Lens
- Lighting Module
- Monitor, keyboard & mouse

Options

- Custom Lens/Working Distance
 - PC or Rackmount Enclosure
 - Special Adaptations
- AVT offers a range of options to meet your needs. Contact our office for details.*

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